Dual Inverter, Open Drain

The NLX2G06 MiniGate[™] is an advanced high-speed CMOS dual inverter with open drain output in ultra-small footprint.

The NLX2G06 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 2.4 \text{ ns (Typ)} @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

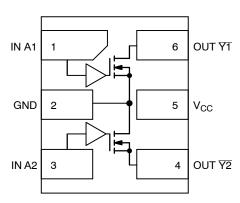


Figure 1. Pinout (Top View)

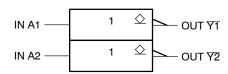


Figure 2. Logic Symbol

PIN ASSIGNMENT

1	IN A1			
2	GND			
3	IN A2			
4	OUT Y2			
5	V _{CC}			
6	OUT Y1			

FUNCTION TABLE

Α	₹					
L H	Z L					



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS



ULLGA6 1.0 x 1.0 CASE 613AD





ULLGA6 1.2 x 1.0 CASE 613AE





ULLGA6 1.45 x 1.0 CASE 613AF





UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.2 x 1.0 CASE 517AA





UDFN6 1.45 x 1.0 CASE 517AQ



P = Device Marking M = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V	
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
l _{ok}	DC Output Diode Current	-50	mA	
I _O	DC Output Source/Sink Current	±50	mA	
I _{CC}	DC Supply Current Per Supply Pin	±100	mA	
I _{GND}	DC Ground Current per Ground Pin	±100	mA	
T _{STG}	Storage Temperature Range	−65 to +150	°C	
TL	Lead Temperature, 1 mm from Case for 10 Second	ds	260	°C
TJ	Junction Temperature Under Bias	150	°C	
MSL	Moisture Sensitivity	Level 1		
F _R	Flammability Rating Oxygen	UL 94 V-0 @ 0.125 in		
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND	at 125 °C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
 Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/UESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V	
V _{IN}	Digital Input Voltage	0	5.5	V	
V _{OUT}	Output Voltage			5.5	V
T _A	Operating Free-Air Temperature			+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ \begin{array}{c} V_{CC} = 2.5 \ V \pm 0.2 \ V \\ V_{CC} = 3.3 \ V \pm 0.3 \ V \\ V_{CC} = 5.0 \ V \pm 0.5 \ V \\ \end{array} $			20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

		V _{cc}		Vcc	T _A = 25 °C		T _A = +	-85°C	T _A = -5 +12	55°C to 5°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Low-Level Input Voltage		1.65–1.95	0.75 x V _{CC}			0.75 x V _{CC}		0.75 x V _{CC}		V
	voltage		2.3 to 5.5	0.70 x V _{CC}			0.70 x V _{CC}		0.70 x V _{CC}		
V_{IL}	Low-Level Input Voltage		1.65–1.95			0.25 x V _{CC}		0.25 x V _{CC}		0.25 x V _{CC}	٧
	voltage		2.3 – 5.5			0.30 x V _{CC}		0.30 x V _{CC}		0.30 x V _{CC}	
V _{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 100 \mu A$	1.65 – 5.5			0.1		0.1		0.1	V
	voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OH} = 4 \text{ mA} \\ &I_{OH} = 8 \text{ mA} \\ &I_{OH} = 12 \text{ mA} \\ &I_{OH} = 16 \text{ mA} \\ &I_{OH} = 24 \text{ mA} \\ &I_{OH} = 32 \text{ mA} \end{aligned}$	1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.2 0.22 0.28 0.38 0.42	0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55	
I _{LKG}	Z-State Output Leakage Current	$V_{IN} = V_{IL},$ $V_{OUT} = V_{CC}$ or GND	5.5			±5.0		±10		±10	μΑ
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
l _{OFF}	Power-Off Output Leakage Current	V _{IN} or V _{OUT} = 5.5 V	0			1.0		10		10	μΑ
I _{CC}	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		10		10	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

		Vec	V _{CC} Test T _A = 2		T _A = 25 °C		T _A = - to +1		
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Unit
t _{PZL}	Propagation Delay (Figures 3 and 4)	1.65–1.95	$R_L = R_1 = 5000 \ \Omega,$ $C_L = 15 \ pF$	2.0	5.7	10.5	2.0	11	ns
		2.3-2.7	$R_L = R_1 = 500 \Omega,$ $C_L = 50 pF$	0.8	3.0	3.6	0.8	4.1	
		3.0-3.6	$R_L = R_1 = 500 \Omega,$ $C_L = 50 pF$	0.8	2.4	3.2	0.8	3.7	
		4.5–5.5	$R_L = R_1 = 500 \Omega,$ $C_L = 50 pF$	0.5	2.4	3.0	0.5	3.5	
t _{PLZ}	Propagation Delay (Figures 3 and 4)	1.65–1.95	$R_L = R_1 = 500 \Omega,$ $C_L = 50 pF$		5.7	10.5		11	ns
		2.3-2.7	$R_L = R_1 = 500 \ \Omega,$ $C_L = 50 \ pF$		3.8	3.6		4.1	
		3.0-3.6	$R_L = R_1 = 500 \Omega,$ $C_L = 50 pF$		2.9	3.2		3.7	
		4.5–5.5	$R_L = R_1 = 500 \Omega,$ $C_L = 50 pF$		1.2	3.0		3.5	
C _{IN}	Input Capacitance	5.5	V _{IN} = 0 V or V _{CC}		2.5				pF
C _{OUT}	Output Capacitance	5.5	V _{IN} = 0 V or V _{CC}		4				pF
C _{PD}	Power Dissipation Capacitance (Note 6)	3.3 5.5	10 MHz V _{IN} = 0 V or V _{CC}		4				pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

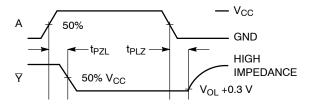
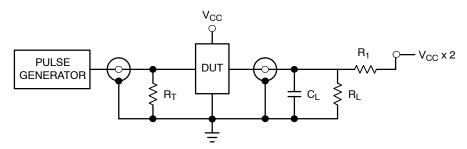


Figure 3. Switching Waveforms



 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

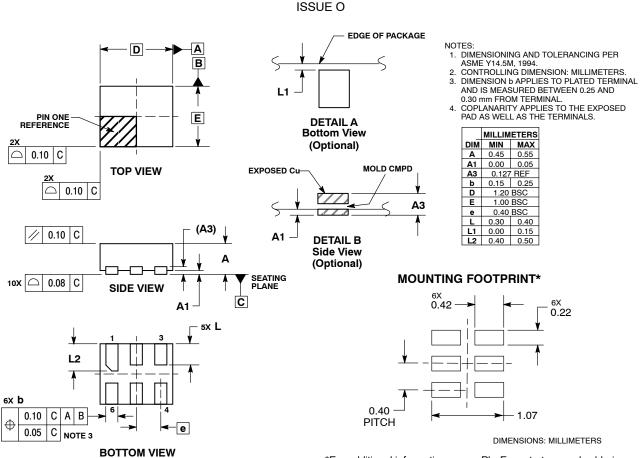
ORDERING INFORMATION

Device	Package	Shipping [†]
NLX2G06AMX1TCG	ULLGA6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G06BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G06CMX1TCG	ULLGA6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel
NLX2G06MUTCG In Development	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G06AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G06CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

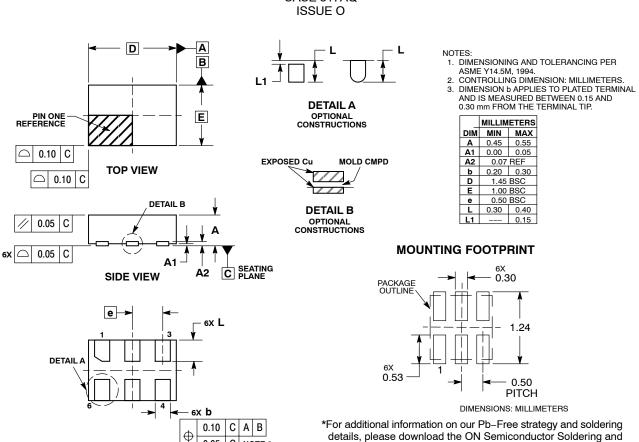
UDFN6 1.2x1.0, 0.4P CASE 517AA



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6 1.45x1.0, 0.5P CASE 517AQ ISSUE O



Mounting Techniques Reference Manual, SOLDERRM/D.

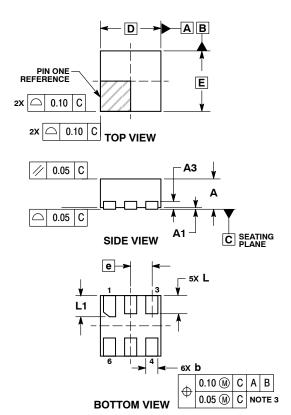
0.05

BOTTOM VIEW

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PACKAGE DIMENSIONS

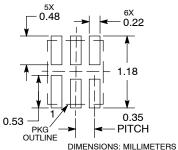
UDFN6 1.0x1.0, 0.35P CASE 517BX ISSUE O



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
 4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS						
DIM	MIN	MAX					
Α	0.45	0.55					
A1	0.00	0.05					
А3	0.13 REF						
b	0.12	0.22					
D	1.00	BSC					
E	1.00	BSC					
е	0.35 BSC						
L	0.25	0.35					
L1	0.30	0.40					

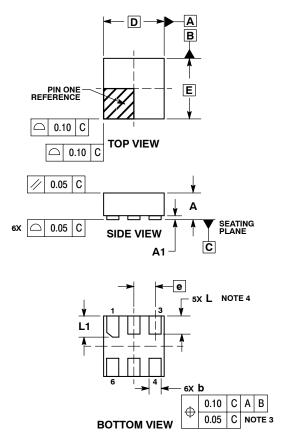
RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.0x1.0, 0.35P CASE 613AD ISSUE A



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 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

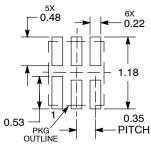
 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALL OWED.
- PACKAGE IS ALLOWED.

	MILLIMETERS				
DIM	MIN	MAX			
Α	-	0.40			
A1	0.00	0.05			
b	0.12	0.22			
D	1.00	BSC			
Е	1.00 BSC				
е	0.35 BSC				
Ĺ	0.25	0.35			
L1	0.30	0.40			

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

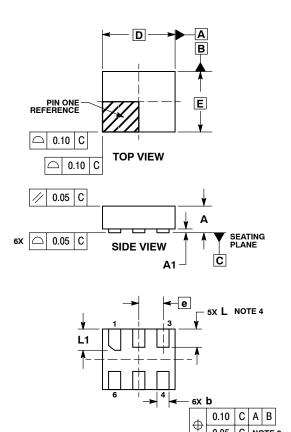


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.2x1.0, 0.4P CASE 613AE ISSUE A



BOTTOM VIEW

0.05 C NOTE 3

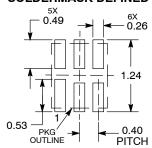
NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS						
DIM	MIN	MAX					
Α		0.40					
A1	0.00	0.05					
b	0.15	0.25					
D	1.20 BSC						
E	1.00 BSC						
е	0.40 BSC						
L	0.25	0.35					
L1	0.35	0.45					

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

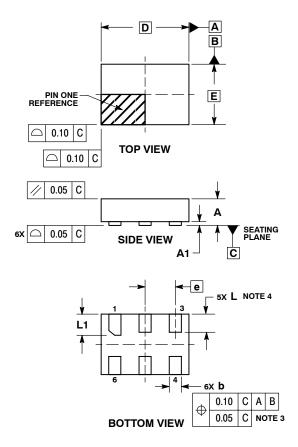


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.45x1.0, 0.5P CASE 613AF **ISSUE A**

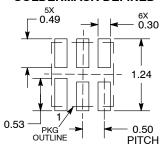


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 ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION & APPLIES TO PLATED TERMINAL
 AND IS MESURED BETWEEN 0.15 AND
 0.30 mm FROM THE TERMINAL TIP.
- A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS					
DIM	MIN	MAX				
Α	-	0.40				
A1	0.00	0.05				
b	0.15	0.25				
D	1.45 BSC					
E	1.00 BSC					
е	0.50 BSC					
Ĺ	0.25	0.35				
L1	0.30	0.40				

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

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028192B 042140C 051117G 070519XB 065312DB 091056E 098456D NL17SG07DFT2G NL17SG17DFT2G NL17SG34DFT2G
NL17SZ07P5T5G NL17SZ125P5T5G NLU1GT126AMUTCG NLV27WZ16DFT2G 5962-8982101PA 5962-9052201PA 74LVC07ADR2G
MC74VHC1G125DFT1G NL17SH17P5T5G NL17SZ125CMUTCG NLV17SZ07DFT2G NLV37WZ17USG NLVHCT244ADTR2G
NC7WZ17FHX 74HCT126T14-13 NL17SH125P5T5G NLV14049UBDTR2G NLV37WZ07USG 74VHC541FT(BE) RHFAC244K1
74LVC1G17FW4-7 74LVC1G126FZ4-7 BCM6302KMLG 74LVC1G07FZ4-7 74LVC1G125FW4-7